

SUBMINIATURE SOLID STATE LAMP

KM-27SURC-03

HYPER RED

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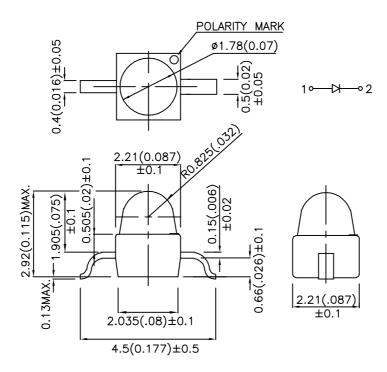
Features

- •SUBMINIATURE PACKAGE.
- •GULL WING.
- •LONG LIFE SOLID STATE RELIABILITY.
- •LOW PACKAGE PROFILE.
- •PACKAGE:1000PCS/REEL.
- •Rohs Compliant.

Description

The Hyper Red source color devices are made with DH InGaAIP on GaAs substrate Light Emitting Diode.

Package Dimensions



Notes:

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is ±0.25(0.01") unless otherwise noted.
- Lead spacing is measured where the leads emerge from the package.
- 4. Specifications are subject to change without notice.

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APPROVED: J. Lu CHECKED: Allen Liu DRAWN: Y.W.WANG

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Selection Guide

Part No.	Dice	Lens Type	lv (mcd) @ 20mA		Viewing Angle
			Min.	Тур.	201/2
KM-27SURC-03	HYPER RED (InGaAIP)	WATER CLEAR	280	1000	20°

Note:

Electrical / Optical Characteristics at Ta=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Hyper Red	640		nm	IF=20mA
λD	Dominant Wavelength	Hyper Red	628		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	Hyper Red	27		nm	IF=20mA
С	Capacitance	Hyper Red	45		pF	VF=0V;f=1MHz
VF	Forward Voltage	Hyper Red	1.9	2.5	V	IF=20mA
lr	Reverse Current	Hyper Red		10	uA	VR = 5V

Absolute Maximum Ratings at Ta=25°C

Parameter	Hyper Red	Units
Power dissipation	170	mW
DC Forward Current	30	mA
Peak Forward Current [1]	185	mA
Reverse Voltage	5	V
Operating / Storage Temperature	-40°C To +85°C	•

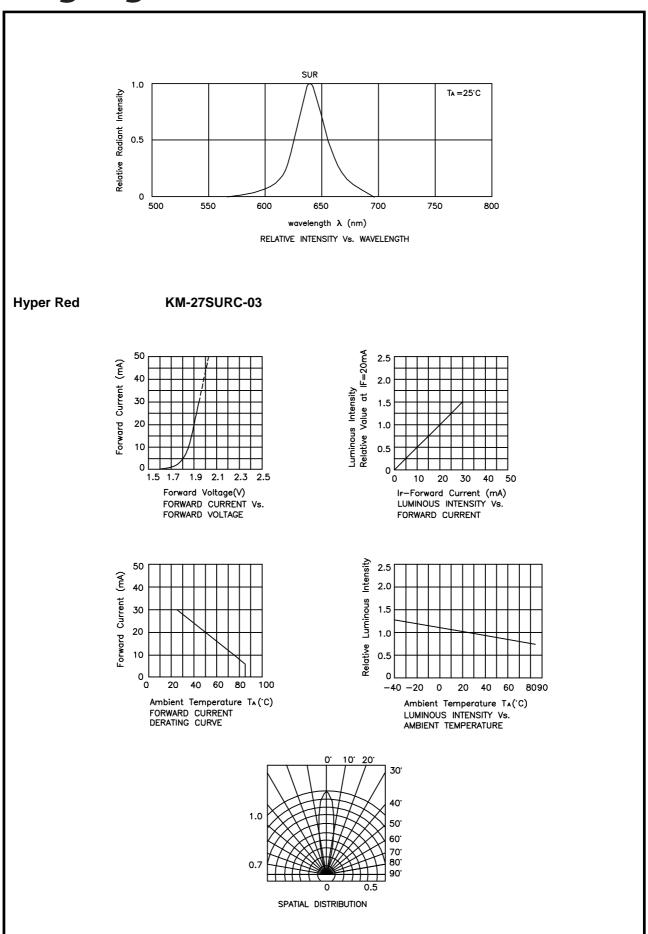
Note:

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 $^{1. \}theta 1/2$ is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.

^{1. 1/10} Duty Cycle, 0.1ms Pulse Width.

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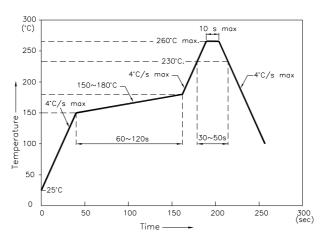


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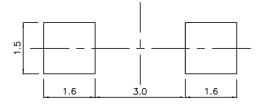
Reflow Soldering Profile For Lead-free SMT Process.



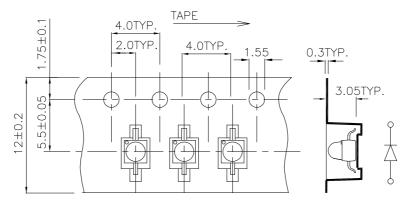
NOTES:

- 1.We recommend the reflow temperature 245°C(+/-5°C).The maximum soldering temperature should be limited to 260°C.
- 2.Don't cause stress to the epoxy resin while it is exposed to high temperature.
- 3. Number of reflow process shall be 2 times or less.

Recommended Soldering Pattern (Units: mm)



Tape Specifications (Units: mm)



Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity, or wavelength), the typical accuracy of the sorting process is as follows:

- 1. Wavelength: +/-1nm
- 2. Luminous Intensity: +/-15%
- 3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

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